PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company	STMicroelectronics International N.V
1.2 PCN No.	MDG/16/9942
1.3 Title of PCN	STM32F7x 2MB - die minor revision & Optimized substrate layout on TFBGA package only
1.4 Product Category	Change 1 : STM32F7x 2MB family products, all products listed in this PCN. Change 2 : STM32F7x 2MB family products in TFBGA package, so only STM32F7xNxH commercial products listed in this PCN.
1.5 Issue date	2016-11-17

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	FRANK WOLINSKI
2.1.2 Phone	+49 89460062287
2.1.3 Email	frank.wolinski@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Michel BUFFA
2.1.2 Marketing Manager	Daniel COLONNA
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	**3.2 Type of change**	**3.3 Manufacturing Location**
Die redesign	Mask or mask set change with new die design	Change 1 : diffusion plant, Crolles 300 (France) Change 2 : assembly plant, Amkor ATP3 (Philippines)

4. Description of change

	Old	**New**
4.1 Description	Change 1 : Die with revision A. Change 2: LSE high driving and low driving capability is not usable for TFBGA package under certain conditions. Both limitations are described in Errata sheet Revision 3 for STM32F76xxx STM32F77xxx products - DocID028806	Change 1: Die with revision Z. Change 2: New substrate layout on TFBGA package products, to fix LSE high driving and low driving limitations. Both changes are implemented at the same time and cannot be accepted independently. Both changes are described in Errata sheet Revision 4 for STM32F76xxx STM32F77xxx products - DocID028806.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	Change 1 & 2 : Function : improvements are indicated in Errata sheet	

5. Reason / motivation for change

5.1 Motivation	To increase the robustness and improve performances, the quality and the functionality of our products. We are introducing a new die revision which optimize the substrate design for the TFBGA package.
5.2 Customer Benefit	QUALITY IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	The die revision changes from "A" to "Z". It is marked on packages of the part.

7. Timing / schedule

7.1 Date of qualification results	2016-11-15
7.2 Intended start of delivery	2017-02-15
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation			
8.1 Description	PCN9942_Die_451XXXZ_Qualification_plan.pptx		
8.2 Qualification report and qualification results	Available (see attachment)	**Issue Date**	2016-11-17

9. Attachments (additional documentations)
9942PpPrdtLst.pdf PCN9942_Die_451XXXZ_Qualification_plan.pptx PCN9942_Additional information.pdf

10. Affected parts		
10. 1 Current		**10.2 New (if applicable)**
10.1.1 Customer Part No	**10.1.2 Supplier Part No**	**10.1.2 Supplier Part No**
	STM32F767IIT6	
	STM32F769IIT6	

IMPORTANT NOTICE – PLEASE READ CAREFULLY